

**DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

**Product Summary**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$ $T_A = 25^\circ C$
24V	15mΩ @ $V_{GS} = 4.5V$	6.5A
	20mΩ @ $V_{GS} = 2.5V$	5.6A

**Description and Applications**

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

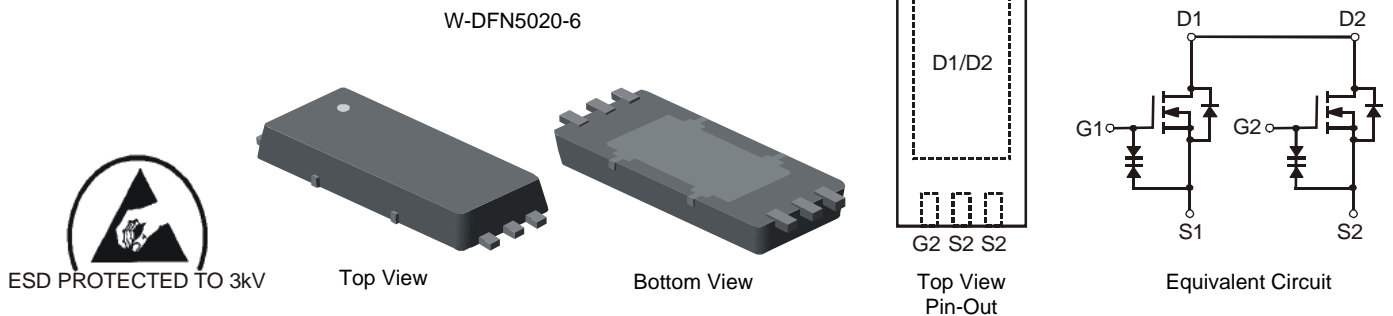
- DC-DC Converters
- Power management functions

**Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **ESD Protected up to 3kV**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: W-DFN5020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.03 grams (approximate)



**Ordering Information (Note 3)**

Part Number	Case	Packaging
DMG5802LFX-7	W-DFN5020-6	3000 / Tape & Reel

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
  3. For packaging details, go to our website at <http://www.diodes.com>.

**Marking Information**



ME = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: X = 2010)  
 M = Month (ex: 9 = September)

Date Code Key

Year	2010	2011	2012	2013	2014	2015	2016
Code	X	Y	Z	A	B	C	D

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	24	V
Gate-Source Voltage			$V_{GSS}$	$\pm 12$	V
Continuous Drain Current (Note 4) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = 25^\circ\text{C}$	$I_D$	6.5	A
		$T_A = 70^\circ\text{C}$		5.2	
Continuous Drain Current (Note 4) $V_{GS} = 2.5\text{V}$	Steady State	$T_A = 25^\circ\text{C}$	$I_D$	5.6	A
		$T_A = 70^\circ\text{C}$		4.5	
Pulsed Drain Current (Note 5)			$I_{DM}$	70	A

**Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 4)	$P_D$	0.98	W
Thermal Resistance, Junction to Ambient @ $T_A = 25^\circ\text{C}$ (Note 4)	$R_{\theta JA}$	126.5	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** @  $T_A = 25^\circ\text{C}$  unless otherwise stated

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	24	-	-	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = 25^\circ\text{C}$	$I_{DSS}$	-	-	1.0	$\mu\text{A}$	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	-	-	$\pm 10$	$\mu\text{A}$	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	0.6	0.9	1.5	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	-	11	15	m $\Omega$	$V_{GS} = 4.5\text{V}, I_D = 6.5\text{A}$
		-	12	17		$V_{GS} = 4\text{V}, I_D = 5.6\text{A}$
		-	13	18		$V_{GS} = 3.1\text{V}, I_D = 5.6\text{A}$
		-	14	20		$V_{GS} = 2.5\text{V}, I_D = 5.6\text{A}$
Forward Transfer Admittance	$ Y_{fs} $	-	17	-	S	$V_{DS} = 5\text{V}, I_D = 6.5\text{A}$
Diode Forward Voltage	$V_{SD}$	-	0.6	0.9	V	$V_{GS} = 0\text{V}, I_S = 1\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	$C_{iss}$	-	1066.4	-	pF	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	132.0	-		
Reverse Transfer Capacitance	$C_{rss}$	-	127.1	-		
Gate Resistance	$R_g$	-	1.47	-	$\Omega$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge $V_{GS} = 4.5\text{V}$	$Q_g$	-	14.5	-	nC	$V_{GS} = 4.5\text{V}, V_{DS} = 15\text{V}, I_D = 5.8\text{A}$
Total Gate Charge $V_{GS} = 10\text{V}$	$Q_{g1}$	-	31.3	-		
Gate-Source Charge	$Q_{gs}$	-	2.0	-		
Gate-Drain Charge	$Q_{gd}$	-	3.1	-		
Turn-On Delay Time	$t_{D(on)}$	-	3.69	-	ns	$V_{GS} = 10\text{V}, V_{DS} = 15\text{V}, R_L = 2.1\Omega, R_G = 3\Omega$
Turn-On Rise Time	$t_r$	-	13.43	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	32.18	-	ns	
Turn-Off Fall Time	$t_f$	-	22.45	-	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
  - Repetitive rating, pulse width limited by junction temperature.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.

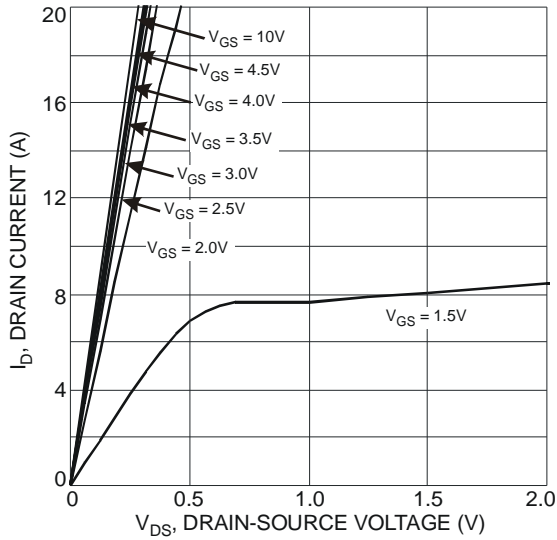


Fig. 1 Typical Output Characteristic

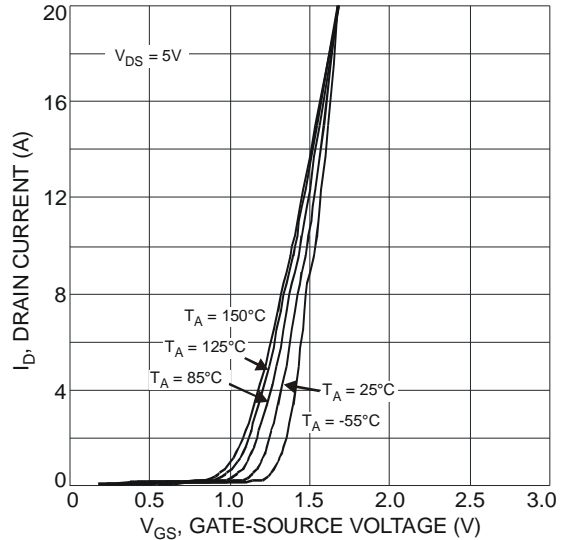


Fig. 2 Typical Transfer Characteristic

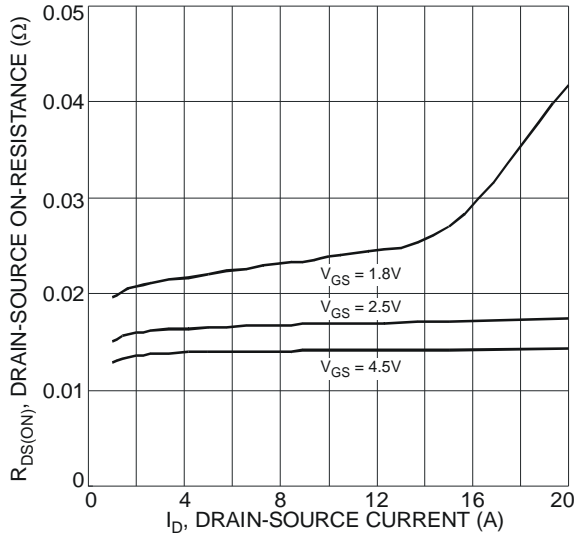


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

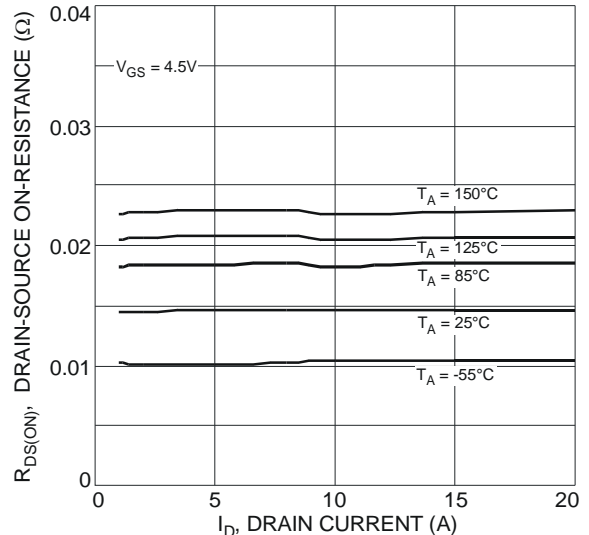


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

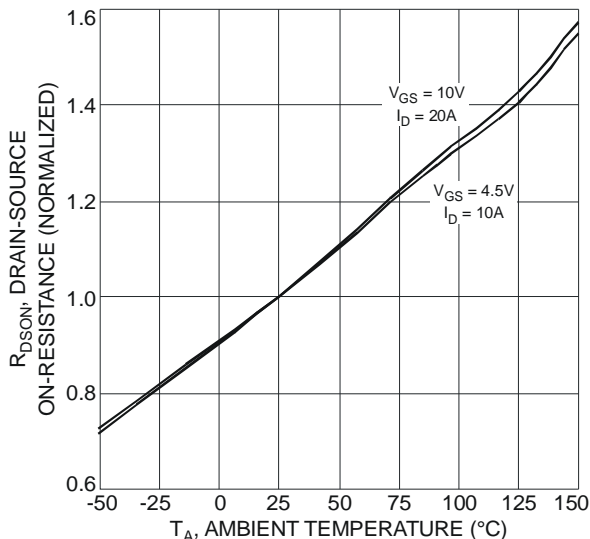


Fig. 5 On-Resistance Variation with Temperature

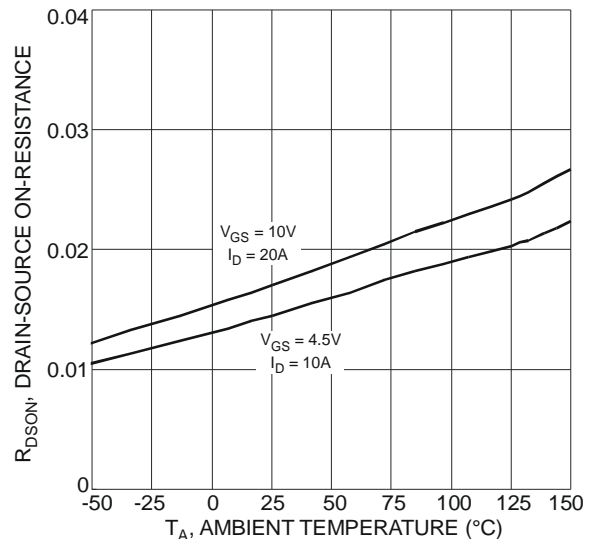


Fig. 6 On-Resistance Variation with Temperature

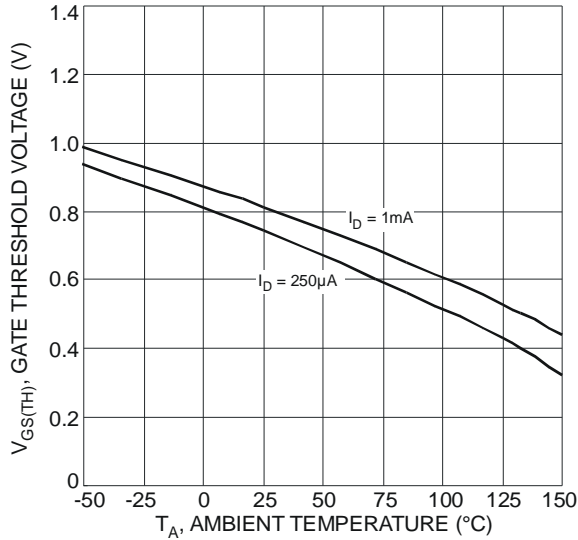


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

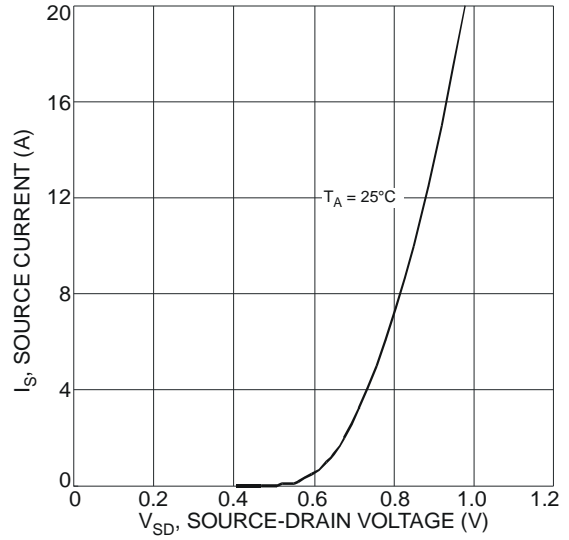


Fig. 8 Diode Forward Voltage vs. Current

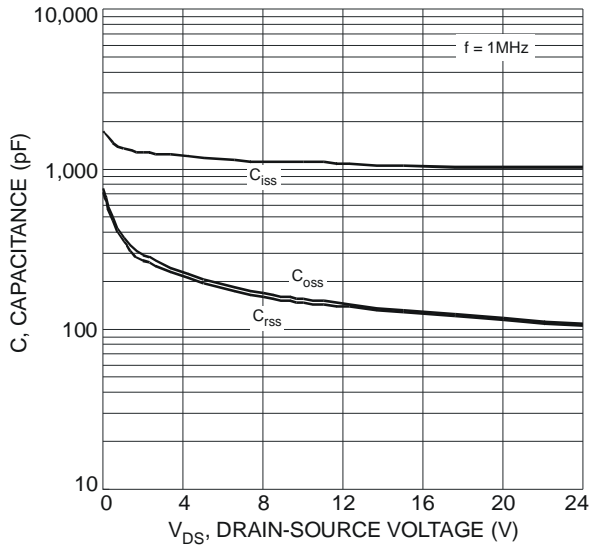


Fig. 9 Typical Total Capacitance

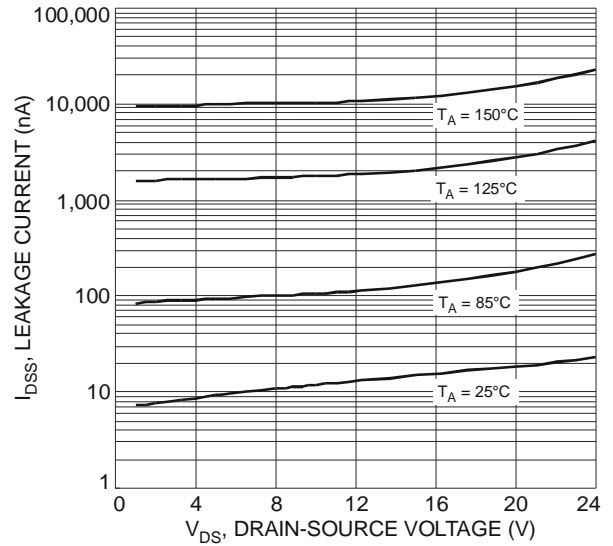


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

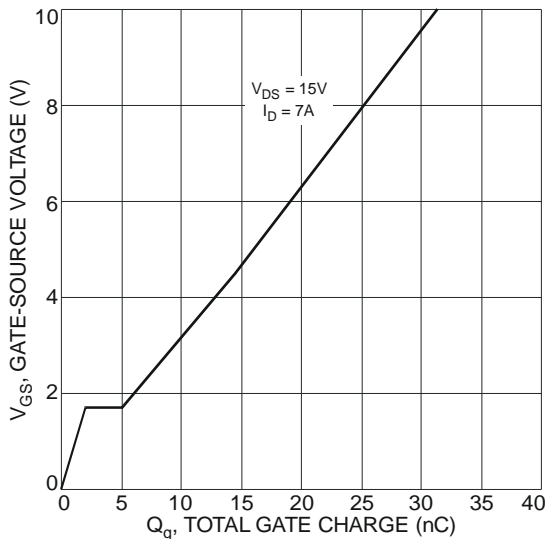


Fig. 11 Gate-Charge Characteristics

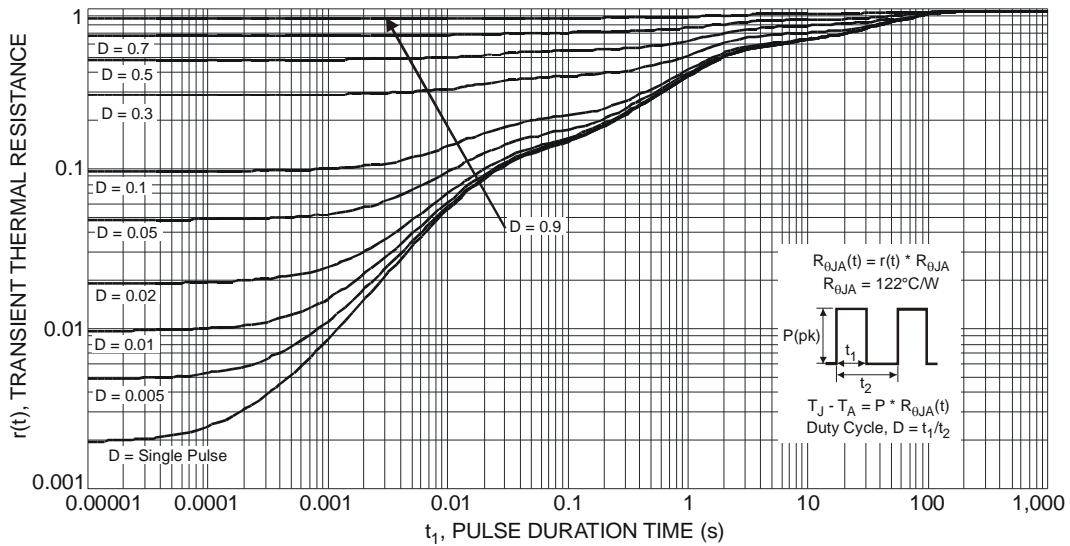
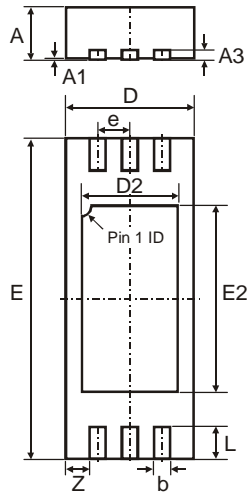


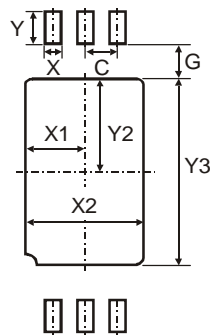
Fig. 12 Transient Thermal Response

**Package Outline Dimensions**



W-DFN5020-6			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.20	0.30	0.25
D	1.90	2.10	2.00
D2	1.40	1.60	1.50
e	-	-	0.50
E	4.90	5.10	5.00
E2	2.80	3.00	2.90
L	0.35	0.65	0.50
Z	-	-	0.375
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
C	0.50
G	0.35
X	0.35
X1	0.90
X2	1.80
Y	0.70
Y2	1.60
Y3	3.20

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